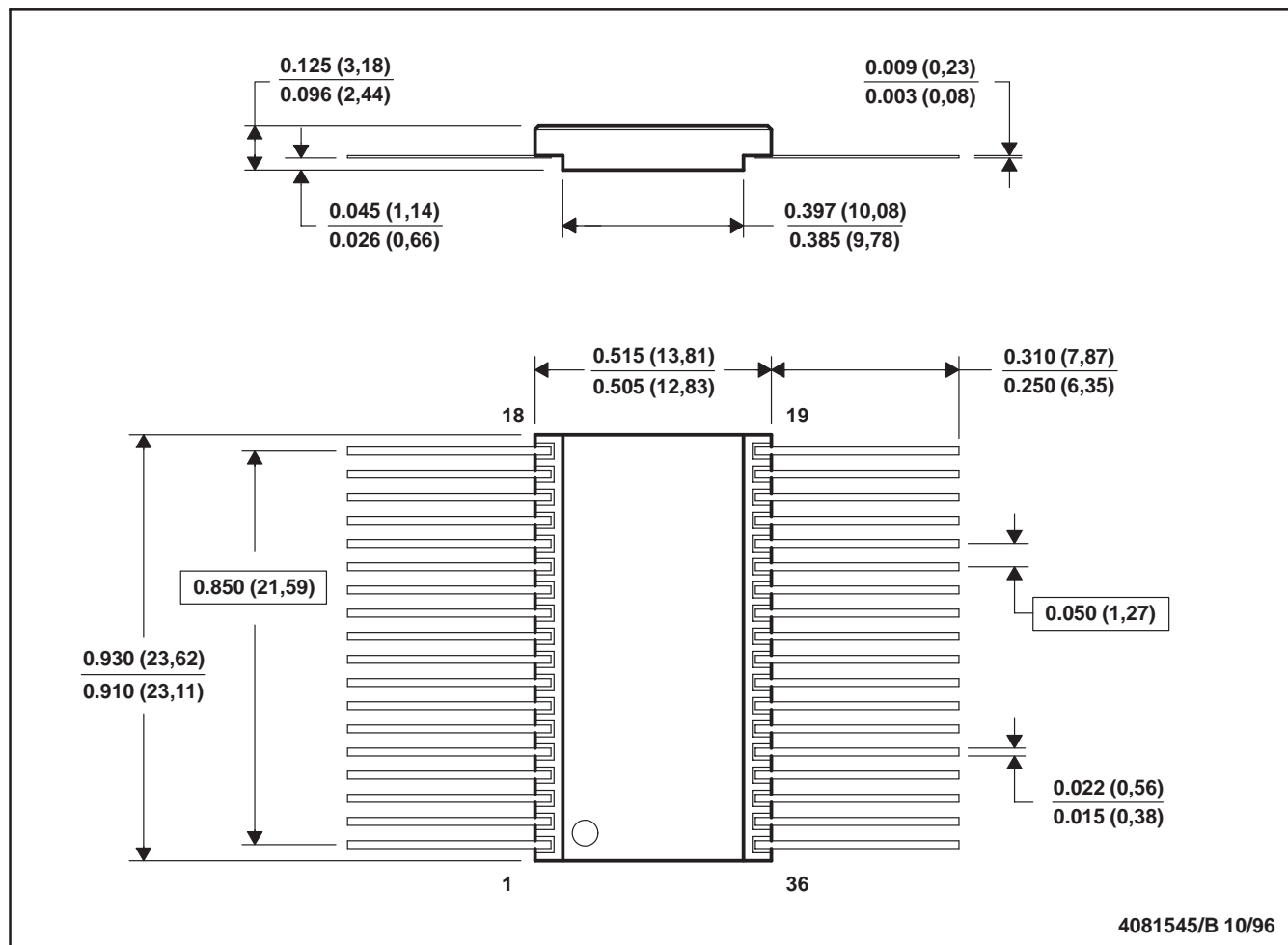


## HKE (R-CDFP-F36)

## CERAMIC DUAL FLATPACK



NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.

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